

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1688	(257/724).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/21 10:54
S2	1813	(257/686).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/21 12:59
S3	2	("20040183187").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/21 13:08
S4	15860	("integrated circuit" or chip or ic) and (dam or ring) and capacitor and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:10
S5	651	("integrated circuit" or chip or ic) and (dam or ring) and capacitor and via and abutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 13:18
S6	13360	("integrated circuit" or "semiconductor chip" or ic) and (dam or ring) and capacitor and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 14:17
S8	3688	("integrated circuit" or "semiconductor chip" or ic) and (metal adj (dam or ring))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 14:19
S9	397	("integrated circuit" or "semiconductor chip" or ic) and (metal adj (dam or ring)) and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 09:52

S10	29	("integrated circuit" or "semiconductor chip" or ic) and (metal adj dam) and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/21 14:26
S13	9717	capacitor same ("printed circuit board" or pbc)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:09
S14	312	capacitor same ("printed circuit board" or pbc) same embedded	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:10
S15	103	capacitor same ("printed circuit board" or pbc) near4 embedded	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:10
S16	90	capacitor same ("printed circuit board" or pbc) near3 embedded	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:10
S17	72	capacitor same ("printed circuit board" or pbc) near2 embedded	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:10
S18	49	(capacitor same ("printed circuit board" or pbc)) near2 embedded	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/22 09:10

S19	64	(US-20010017410-\$ or US-20010054758-\$ or US-20020017721-\$ or US-20020053728-\$ or US-20020100611-\$ or US-20030001252-\$ or US-20030025199-\$ or US-20030137046-\$ or US-20030141582-\$ or US-20030141583-\$ or US-20040007771-\$ or US-20040012085-\$ or US-20040041249-\$ or US-20040090758-\$ or US-20040104463-\$ or US-20040135242-\$ or US-20040145044-\$ or US-20040155325-\$ or US-20040178484-\$ or US-20040183187-\$ or US-20040227250-\$ or US-20040238934-\$ or US-20040251530-\$ or US-20040251531-\$ or US-20050001303-\$ or US-20050006745-\$).did. or (US-20050051884-\$ or US-20050056923-\$ or US-20050067696-\$).did. or (US-5159433-\$ or US-5422435-\$ or US-5535101-\$ or US-5963429-\$ or US-6005778-\$ or US-6069407-\$ or US-6100594-\$ or US-6130823-\$ or US-6150724-\$ or US-6153928-\$ or US-6265765-\$ or US-6265771-\$ or US-6274930-\$ or US-6309915-\$ or US-6333563-\$ or US-6335491-\$ or US-6344687-\$ or US-6365963-\$ or US-6399420-\$ or US-6404062-\$ or US-6441476-\$ or US-6445064-\$ or US-6509633-\$ or US-6555917-\$ or US-6603182-\$ or US-6603193-\$). did. or (US-6606793-\$ or US-6664617-\$ or US-6683795-\$ or US-6717253-\$ or US-6734551-\$ or US-6737742-\$ or US-6768190-\$ or US-6849940-\$ or US-6861288-\$). did.	US-PGPUB; USPAT	OR	ON	2005/08/04 09:17
S20	15916	substrate with reinforc\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 09:53

S21	36	substrate with reinforcement\$3 with interposer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 10:06
S22	153	substrate and (interposer with embedded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 10:49
S23	1403	substrate and (reinforcement\$3 with embedded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/04 10:49
S24	382	substrate same (reinforcement\$3 with embedded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 14:45
S25	2037525	substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/05 14:45